

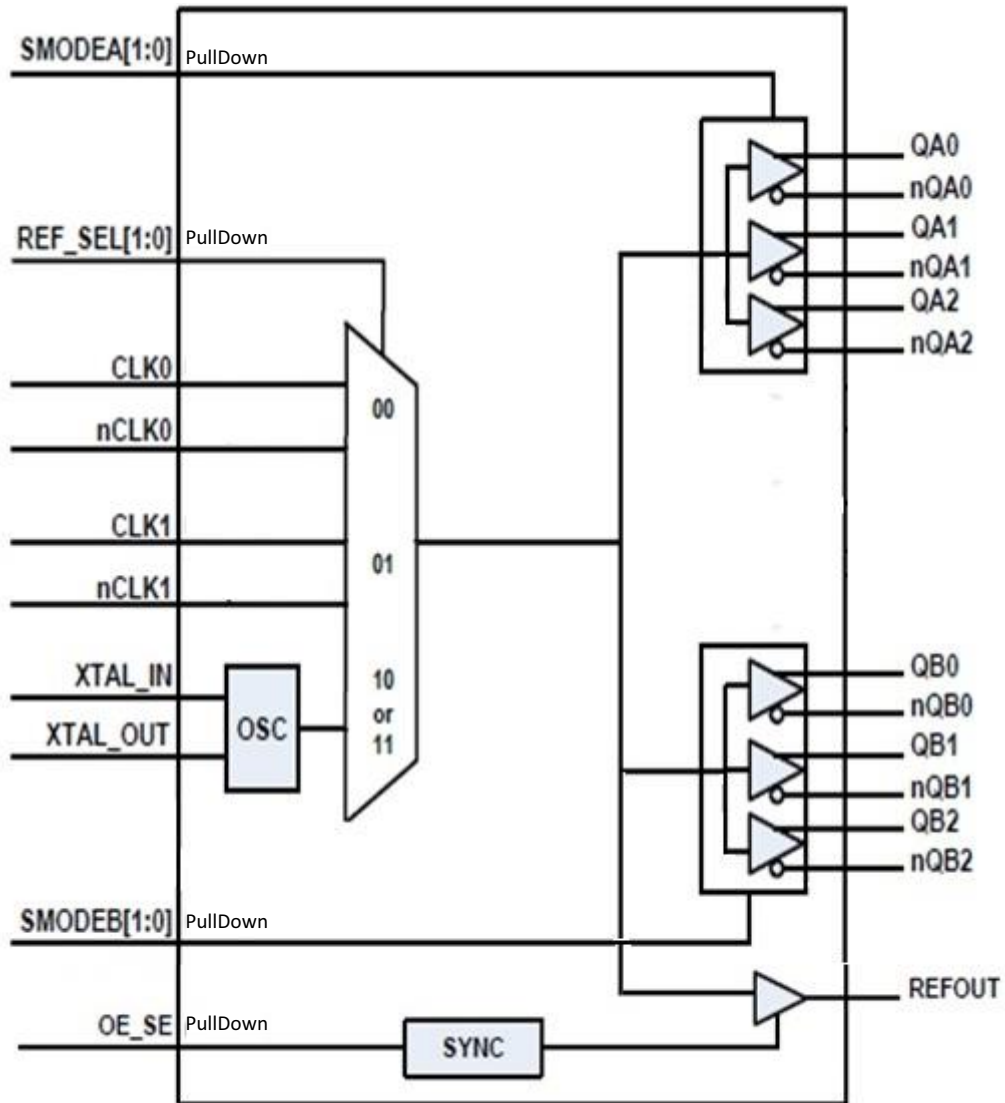
## Description

The 8T39S06A is a high-performance clock fanout buffer. The input clock can be selected from two differential inputs or one crystal input. The internal oscillator circuit is automatically disabled if the crystal input is not selected. The crystal pin can be driven by a single-ended clock. The selected signal is distributed to six differential outputs which can be configured as LVPECL, LVDS or HCSL outputs. In addition, an LVCMOS output is provided. All outputs can be disabled into a high-impedance state. The device is designed for a signal fanout of high-frequency, low phase-noise clock and data signal. The outputs are at a defined level when inputs are open or tied to ground. It is designed to operate from a 3.3V or 2.5V core power supply, and either a 3.3V or 2.5V output operating supply.

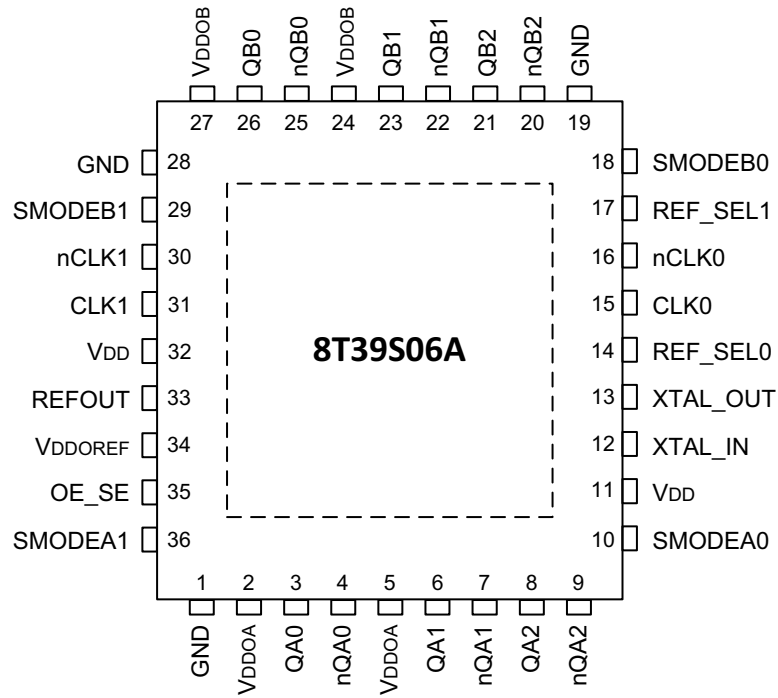
## Features

- Two differential reference clock input pairs
- Differential input pairs can accept the following input levels: LVPECL, LVDS, HCSL, HSTL and Single-ended
- Crystal Oscillator Interface
- Crystal input frequency range: 10MHz to 40MHz
- Maximum Output Frequency:
  - LVPECL – 2GHz
  - LVDS – 2GHz
  - HCSL – 250MHz
  - LVCMOS – 250MHz
- Two banks, each has three differential output pairs that can be configured as LVPECL or LVDS or HCSL
- One single-ended reference output with synchronous enable to avoid clock glitch
- Output skew: 80ps (maximum)  
(Bank A and Bank B at the same output level)
- Part-to-part skew: 200ps (typical)
- Additive RMS phase jitter at 156.25MHz, (12kHz–20MHz):  
34.7fs (typical), 3.3V/ 3.3V
- Supply voltage modes:
  - $V_{DD}/V_{DDO}$
  - 3.3V/3.3V
  - 3.3V/2.5V
  - 2.5V/2.5V
- -40°C to +85°C ambient operating temperature
- Lead-free (RoHS 6) packaging

# Block Diagram



## Pin Assignment



**36-pin, 6mm x 6mm VFQFN Package**

## Pin Description and Pin Characteristic Tables

Table 1: Pin Descriptions

Number	Name	Type		Description
1	GND	Power		Power supply ground.
2	V <sub>DDOA</sub>	Power		Output supply pin for Bank QA outputs.
3	QA0	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
4	nQA0	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
5	V <sub>DDOA</sub>	Power		Output supply pin for Bank QA outputs.
6	QA1	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
7	nQA1	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
8	QA2	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
9	nQA2	Output		Differential Bank A clock output pair. LVPECL, LVDS or HCSL interface levels.
10	SMODEA0	Input	Pulldown	Output driver select for Bank A outputs. See <a href="#">Table 8</a> for function. LVCMOS/LVTTL interface levels.
11	V <sub>DD</sub>	Power		Power supply pin.
12	XTAL_IN	Input		Crystal oscillator interface.
13	XTAL_OUT	Output		Crystal oscillator interface.
14	REF_SEL0	Input	Pulldown	Input clock selection. LVCMOS/LVTTL interface levels. See <a href="#">Table 3</a> for function.
15	CLK0	Input	Pullup/ Pulldown	Non-inverting differential clock. Internally biased to 0.33V <sub>DD</sub> .
16	nCLK0	Input	Pullup/ Pulldown	Inverting differential clock. Internally biased to 0.4V <sub>DD</sub> .
17	REF_SEL1	Input	Pulldown	Input clock selection. LVCMOS/LVTTL interface levels. See <a href="#">Table 3</a> for function.
18	SMODEB0	Input	Pulldown	Output driver select for Bank B outputs. See <a href="#">Table 9</a> for function. LVCMOS/LVTTL interface levels.
19	GND	Power		Power supply ground.
20	nQB2	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
21	QB2	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
22	nQB1	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
23	QB1	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
24	V <sub>DDOB</sub>	Power		Output supply pin for Bank QB outputs.
25	nQB0	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
26	QB0	Output		Differential Bank B clock output pair. LVPECL, LVDS or HCSL interface levels.
27	V <sub>DDOB</sub>	Power		Output supply pin for Bank QB outputs.
28	GND	Power		Power supply ground.
29	SMODEB1	Input	Pulldown	Output driver select for Bank B outputs. See <a href="#">Table 9</a> for function. LVCMOS/LVTTL interface levels.
30	nCLK1	Input	Pullup/ Pulldown	Inverting differential clock. Internally biased to 0.4V <sub>DD</sub> .
31	CLK1	Input	Pullup/ Pulldown	Non-inverting differential clock. Internally biased to 0.33V <sub>DD</sub> .
32	V <sub>DD</sub>	Power		Power supply pin.

Number	Name	Type		Description
33	REFOUT	Output		Single-ended reference clock output. LVCMOS/LVTTL interface levels.
34	V <sub>DDOREF</sub>	Power		Output supply pin for REFOUT output.
35	OE_SE	Input	Pulldown	Output enable. LVCMOS/LVTTL interface levels. See <a href="#">Table 4</a> .
36	SMODEA1	Input	Pulldown	Output driver select for Bank A outputs. See <a href="#">Table 8</a> for function. LVCMOS/LVTTL interface levels.
0	ePAD	Power		Connect ePAD to ground to ensure proper heat dissipation.

NOTE: *Pulldown* and *Pullup* refer to an internal input resistors. See [Table 2, Pin Characteristics](#), for typical values.

**Table 2: Pin Characteristics**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
C <sub>IN</sub>	Input Capacitance	OE_SE, SMODEx[1:0], REF_SEL[1:0]			2		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor				50		kΩ
R <sub>PULLUP</sub>	Input Pullup Resistor	CLK0, CLK1			100		kΩ
		nCLK0, nCLK1			75		kΩ
C <sub>PD</sub>	Power Dissipation Capacitance	REFOUT	V <sub>DDOREF</sub> = 3.465V		5.3		pF
			V <sub>DDOREF</sub> = 2.625V		6.3		pF
R <sub>OUT</sub>	Output Impedance	REFOUT	V <sub>DDOREF</sub> = 3.3V		52		Ω
			V <sub>DDOREF</sub> = 2.5V		63		Ω

## Function Tables

**Table 3: REF\_SELx Function Table**

Control Input	Selected Input Reference Clock
REF_SEL[1:0]	
00 (default)	CLK0, nCLK0
01	CLK1, nCLK1
10	XTAL
11	XTAL

**Table 4: OE\_SE Function Table**

OE_SE	REFOUT
0 (default)	High-Impedance
1	Enabled

NOTE: Synchronous output enable to avoid clock glitch.

**Table 5: Input/Output Operation Table, OE\_SE**

Input Status			Output State
OE_SE	REF_SEL [1:0]	CLKx and nCLKx	REFOUT
0 (default)	Don't care	Don't Care	High-Impedance
1	10 or 11	Don't Care	Fanout Crystal Oscillator
1	00 (default)	CLK0 and nCLK0 are both open circuit	Logic Low
		CLK0 and nCLK0 are tied to ground	Logic Low
		CLK0 is high, nCLK0 is low	Logic High
		CLK0 is low, nCLK0 is high	Logic Low
1	01	CLK1 and nCLK1 are both open circuit	Logic Low
		CLK1 and nCLK1 are tied to ground	Logic Low
		CLK1 is high, nCLK1 is low	Logic High
		CLK1 is low, nCLK1 is high	Logic Low

**Table 6: Input/Output Operation Table, SMODEA**

Input Status			Output State
SMODEA[1:0]	REF_SEL[1:0]	CLKx and nCLKx	QA[2:0], nQA[2:0]
11	Don't care	Don't Care	High Impedance
00, 01 or 10	10 or 11	Don't Care	Fanout Crystal Oscillator
00, 01 or 10	00 (default)	CLK0 and nCLK0 are both open circuit	QA[2:0] = Low nQA[2:0] = High
		CLK0 and nCLK0 are tied to ground	QA[2:0] = Low nQA[2:0] = High
		CLK0 is high, nCLK0 is low	QA[2:0] = High nQA[2:0] = Low
		CLK0 is low, nCLK0 is high	QA[2:0] = Low nQA[2:0] = High
00, 01 or 10	01	CLK1 and nCLK1 are both open circuit	QA[2:0] = Low nQA[2:0] = High
		CLK1 and nCLK1 are tied to ground.	QA[2:0] = Low nQA[2:0] = High
		CLK1 is high, nCLK1 is low	QA[2:0] = High nQA[2:0] = Low
		CLK1 is low, nCLK1 is high	QA[2:0] = Low nQA[2:0] = High

**Table 7: Input/Output Operation Table, SMODEB**

Input Status			Output State
SMODEB[1:0]	REF_SEL[1:0]	CLKx and nCLKx	QB[2:0], nQB[2:0]
11	Don't care	Don't Care	High Impedance
00, 01 or 10	10 or 11	Don't Care	Fanout Crystal Oscillator
00, 01 or 10	00 (default)	CLK0 and nCLK0 are both open circuit	QB[2:0] = Low nQB[2:0] = High
		CLK0 and nCLK0 are tied to ground	QB[2:0] = Low nQB[2:0] = High
		CLK0 is high, nCLK0 is low	QB[2:0] = High nQB[2:0] = Low
		CLK0 is low, nCLK0 is high	QB[2:0] = Low nQB[2:0] = High
00, 01 or 10	01	CLK1 and nCLK1 are both open circuit	QB[2:0] = Low nQB[2:0] = High
		CLK1 and nCLK1 are tied to ground	QB[2:0] = Low nQB[2:0] = High
		CLK1 is high, nCLK1 is low	QB[2:0] = High nQB[2:0] = Low
		CLK1 is low, nCLK1 is high	QB[2:0] = Low nQB[2:0] = High

**Table 8: Output Level Selection Table, QA[0:2], nQA[0:2]**

SMODEA1	SMODEA0	Output Type
0	0	LVPECL (default)
0	1	LVDS
1	0	HCSL
1	1	High-Impedance

**Table 9: Output Level Selection Table, QB[0:2], nQB[0:2]**

SMODEB1	SMODEB0	Output Type
0	0	LVPECL (default)
0	1	LVDS
1	0	HCSL
1	1	High-Impedance



## Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$ XTAL_IN Other Inputs	0V to 2V -0.5V to $V_{DD} + 0.5V$
Outputs, $V_O$ , (HCSL, LVCMOS)	-0.5V to $V_{DDOX}^1 + 0.5V$
Outputs, $I_O$ , (LVPECL) Continuous Current Surge Current	50mA 100mA
Outputs, $I_O$ , (LVDS) Continuous Current Surge Current	10mA 15mA
Junction Temperature	125°C
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE 1.  $V_{DDOX}$  denotes  $V_{DDOA}$ ,  $V_{DDOB}$  and  $V_{DDOREF}$ .

## DC Electrical Characteristics

**Table 10: Power Supply DC Characteristics,  $V_{DD} = V_{DDOA} = V_{DDOB} = V_{DDOREF} = 3.3V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ C$  to  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{DD}$	Power Supply Voltage		3.135	3.3	3.465	V
$V_{DDOA}$ , $V_{DDOB}$ , $V_{DDOREF}$	Output Supply Voltage		3.135	3.3	3.465	V
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 01		90	110	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>1</sup>	SMODEA/B[1:0] = 01		125	150	mA
$I_{EE}$	Power Supply Current	SMODEA/B[1:0] = 00 (default)		130	155	mA
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 10		85	105	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>2</sup>	SMODEA/B[1:0] = 10		50	60	mA

NOTE 1. Differential outputs are terminated with 100Ω.

NOTE 2. Differential outputs are running at 250MHz and floating.

**Table 11: Power Supply DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDOA} = V_{DDOB} = V_{DDOREF} = 2.5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{DD}$	Power Supply Voltage		3.135	3.3	3.465	V
$V_{DDOA}$ , $V_{DDOB}$ , $V_{DDOREF}$	Output Supply Voltage		2.375	2.5	2.625	V
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 01		90	110	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>1</sup>	SMODEA/B[1:0] = 01		125	150	mA
$I_{EE}$	Power Supply Current	SMODEA/B[1:0] = 00 (default)		130	155	mA
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 10		85	105	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>2</sup>	SMODEA/B[1:0] = 10		40	50	mA

NOTE 1. Differential outputs are terminated with 100Ω.

NOTE 2. Differential outputs are running at 250MHz and floating.

**Table 12: Power Supply DC Characteristics,  $V_{DD} = V_{DDOA} = V_{DDOB} = V_{DDOREF} = 2.5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{DD}$	Power Supply Voltage		2.375	2.5	2.625	V
$V_{DDOA}$ , $V_{DDOB}$ , $V_{DDOREF}$	Output Supply Voltage		2.375	2.5	2.625	V
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 01		80	95	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>1</sup>	SMODEA/B[1:0] = 01		120	145	mA
$I_{EE}$	Power Supply Current	SMODEA/B[1:0] = 00 (default)		115	140	mA
$I_{DD}$	Power Supply Current	SMODEA/B[1:0] = 10		70	85	mA
$I_{DDOA} + I_{DDOB}$	Output Supply Current <sup>2</sup>	SMODEA/B[1:0] = 10		40	50	mA

NOTE 1. Differential outputs are terminated with 100Ω.

NOTE 2. Differential outputs are running at 250MHz and floating.

**Table 13: LVCMOS/LVTTL DC Characteristics,**

$V_{DD} = 3.3V \pm 5\%$ ,  $2.5V \pm 5\%$ ,  $V_{DDOREF} = 3.3V \pm 5\%$  or  $2.5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit	
$V_{IH}$	Input High Voltage	OE_SE, SMODEA[1:0], SMODEB[1:0], REF_SEL[1:0]	$V_{DD} = 3.3V \pm 5\%$	2		$V_{DD} + 0.3$	V
			$V_{DD} = 2.5V \pm 5\%$	1.7		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage	OE_SE, SMODEA[1:0], SMODEB[1:0], REF_SEL[1:0]	$V_{DD} = 3.3V \pm 5\%$	-0.3		0.8	V
			$V_{DD} = 2.5V \pm 5\%$	-0.3		0.7	V
$I_{IH}$	Input High Current	OE_SE, SMODEA[1:0], SMODEB[1:0], REF_SEL[1:0]	$V_{DD} = V_{IN} = 3.465V$ or $2.625V$		150	μA	

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$I_{IL}$	Input Low Current	OE_SE, SMODEA[1:0], SMODEB[1:0], REF_SEL[1:0]	$V_{DD} = 3.465V$ or $2.625V$ , $V_{IN} = 0V$	-5			$\mu A$
$V_{OH}$	Output High Voltage	REFOUT	$V_{DDOREF} = 3.3V \pm 5\%$ : $I_{OH} = -1mA$	2.6			V
			$V_{DDOREF} = 2.5V \pm 5\%$ : $I_{OH} = -1mA$	1.8			V
$V_{OL}$	Output Low Voltage	REFOUT	$V_{DDOREF} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$ : $I_{OL} = 1mA$			0.5	V

**Table 14: Differential DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$  or  $2.5V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ C$  to  $85^\circ C$**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$I_{IH}$	Input High Current	CLK[1:0], nCLK[1:0]	$V_{DD} = V_{IN} = 3.465V$ or $2.625V$			150	$\mu A$
$I_{IL}$	Input Low Current	CLK[1:0], nCLK[1:0]	$V_{DD} = 3.465V$ or $2.625V$ , $V_{IN} = 0V$	-150			$\mu A$
$V_{PP}$	Peak-to-Peak Input Voltage <sup>1</sup>			0.240		1.3	V
$V_{CMR}$	Common Mode Input Voltage <sup>2 3</sup>			GND		$V_{DD} - 0.85$	V

NOTE 1. Input voltage should not be less than -0.3V and greater than  $V_{DD}$ .

NOTE 2. Common mode voltage is defined as the crosspoint.

NOTE 3.  $V_{IL} > -0.3V$ .

**Table 15: LVPECL DC Characteristics,  $V_{DDOA} = V_{DDOB} = 3.3V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ C$  to  $85^\circ C$ <sup>1</sup>**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$V_{OH}$	Output High Voltage <sup>2</sup>			$V_{DDOX} - 1.4$		$V_{DDOX} - 0.8$	V
$V_{OL}$	Output Low Voltage <sup>2</sup>			$V_{DDOX} - 2.0$		$V_{DDOX} - 1.6$	V
$V_{SWING}$	Peak-to-Peak Output Voltage Swing			0.6		1.0	V

NOTE 1.  $V_{DDOX}$  denotes  $V_{DDOA}$  and  $V_{DDOB}$ .

NOTE 2. Outputs terminated with  $50\Omega$  to  $V_{DDOX} - 2V$ .

**Table 16: LVPECL DC Characteristics,  $V_{DDOA} = V_{DDOB} = 2.5V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ C$  to  $85^\circ C$ <sup>1</sup>**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$V_{OH}$	Output High Voltage <sup>2</sup>			$V_{DDOX} - 1.4$		$V_{DDOX} - 0.8$	V
$V_{OL}$	Output Low Voltage <sup>2</sup>			$V_{DDOX} - 2.0$		$V_{DDOX} - 1.6$	V
$V_{SWING}$	Peak-to-Peak Output Voltage Swing			0.4		1.0	V

NOTE 1.  $V_{DDOX}$  denotes  $V_{DDOA}$  and  $V_{DDOB}$ .

NOTE 2. Outputs terminated with  $50\Omega$  to  $V_{DDOX} - 2V$ .

**Table 17: LVDS DC Characteristics,  $V_{DDOA} = V_{DDOB} = 3.3V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{OD}$	Differential Output Voltage		247		454	mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change			50		mV
$V_{OS}$	Offset Voltage		1.025		1.375	V
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change			50		mV

**Table 18: LVDS DC Characteristics,  $V_{DDOA} = V_{DDOB} = 2.5V \pm 5\%$ , GND = 0V,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{OD}$	Differential Output Voltage		247		454	mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change			50		mV
$V_{OS}$	Offset Voltage		1.025		1.375	V
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change			50		mV

**Table 19: Crystal Characteristics**

Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
Mode of Oscillation		Fundamental			
Frequency		10		40	MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Capacitive Loading ( $C_L$ )			12	18	pF

## AC Electrical Characteristics

**Table 20: AC Characteristics,  $V_{DD} = V_{DDOA} = V_{DDOB} = V_{DDOREF} = 3.3V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$  <sup>1, 2</sup>**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$f_{OUT}$	Output Frequency	LVDS, LVPECL Outputs				2000	MHz
		HCSL Outputs				250	MHz
		REFOUT				250	MHz
$t_{jit}$	Buffer Additive Phase Jitter, RMS: Integration Range 12kHz - 20MHz REF_SEL[1:0] = 00 or 01		Clock Frequency = 156.25MHz; Input Clock from 8T49NS010, Input Clock Jitter = 86.6fs; SMODEA/B[1:0] = 00		34.7		fs
NF	Noise Floor	LVPECL Outputs	Offset Freq. >10MHz; 156.25MHz Clock Freq.		-159.1		dBc/Hz
		LVDS Outputs			-157.0		dBc/Hz
		HCSL Outputs			-156.0		dBc/Hz
$t_{jit}(\emptyset)$	RMS Phase Jitter; 25MHz Integration Range: 100Hz - 1MHz		REF_SEL[1:0] = 10 or 11 <sup>3</sup>		0.176		ps
$t_{PD}$	Propagation Delay <sup>4</sup>	CLK0, nCLK0 or CLK1, nCLK1 to any Qx, nQx Outputs	SMODEA/B[1:0] = 00	0.28		0.75	ns
			SMODEA/B[1:0] = 01	0.28		0.75	ns
			SMODEA/B[1:0] = 10	0.90		2.65	ns
$t_{sk(o)}$	Output Skew <sup>5, 6</sup>					80	ps
$t_{sk(pp)}$	Part-to-Part Skew <sup>6, 7</sup>				200		ps
$V_{OH}$	Voltage High <sup>8, 9</sup>	HCSL Outputs	$T_A = 25^\circ C$ , DC Measurement, $R_T = 50\Omega$ to GND $C_L \leq 5pF$	520		920	mV
$V_{OL}$	Voltage Low <sup>8, 10</sup>	HCSL Outputs		-150		+150	mV
$V_{CROSS}$	Absolute Crossing Voltage <sup>8, 11, 12</sup>	HCSL Outputs	$R_T = 50\Omega$ to GND $C_L \leq 5pF$	160		460	mV
$\Delta V_{CROSS}$	Total Variation of $V_{CROSS}$ over all Edges <sup>8, 11, 13</sup>	HCSL Outputs				140	mV
	Rise/Fall Edge Rate <sup>3, 14, 15</sup>	HCSL Outputs		0.6		4.0	V/ns
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs	20% to 80%		150	300	ps
		LVDS Outputs	20% to 80%		150	300	ps
		HCSL Outputs	20% to 80%		400	650	ps
		REFOUT	20% to 80%		450	750	ps
odc	Output Duty Cycle <sup>16</sup>	with Crystal Input		45		55	%
		with External 50%/ 50% Duty Cycle Clock Input		45		55	%
MUX_ISOLATION	MUX Isolation		156.25MHz		75		dB

NOTE 1. Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 2. All LVDS and LVPECL parameters characterized up to 1.5GHz. HCSL parameters characterized up to 250MHz.

NOTE 3. Measurement taken from differential waveform.

NOTE 4. Measured from the differential input crosspoint to the differential output crosspoint.

NOTE 5. Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the differential crosspoint.

NOTE 6. This parameter is defined in accordance with JEDEC Standard 65.

NOTE 7. Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential crosspoint.

NOTE 8. Measurement taken from single-ended waveform.

NOTE 9. Defined as the maximum instantaneous voltage including overshoot.

NOTE 10. Defined as the minimum instantaneous voltage including undershoot.

NOTE 11. Measured at crosspoint where the instantaneous voltage value of the rising edge of Qx equals the falling edge of nQx.

NOTE 12. Refers to the total variation from the lowest crosspoint to the highest, regardless of which edge is crossing. Refers to all crosspoint for this measurement.

NOTE 13. Defined as the total variation of all crossing voltages of rising Qx and falling nQx, This is the maximum allowed variance in  $V_{cross}$  for any particular system.

NOTE 14. Measured from -150mV to +150mV on the differential waveform (Qx minus nQx). The signal must be monotonic through the measurement region for rise and fall time. The 300mV measurement window is centered on the differential zero crossing.

NOTE 15. Measured at 100MHz.

NOTE 16. Measured for the following frequencies: 25MHz, 100MHz, 125MHz, 156.25MHz, 312.5MHz, 400MHz, and 644.5313MHz.

**Table 21: AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDOA} = V_{DDOB} = V_{DDOREF} = 2.5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$  <sup>1, 2</sup>**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Unit
$f_{OUT}$	Output Frequency	LVDS, LVPECL Outputs				2000	MHz
		HCSL Outputs				250	MHz
		REFOUT				250	MHz
$t_{jit}$	Buffer Additive Phase Jitter, RMS: Integration Range 12kHz - 20MHz REF_SEL[1:0] = 00 or 01		Clock Frequency = 156.25MHz; Input Clock from 8T49NS010, Input Clock Jitter = 86.8fs; SMODEA/B[1:0] = 00		36.7		fs
NF	Noise Floor	LVPECL	Offset Freq. >10MHz; 156.25MHz Clock Freq.		-159.1		dBc/Hz
		LVDS			-157.0		dBc/Hz
		HCSL			-155.7		dBc/Hz
$t_{jit}(\emptyset)$	RMS Phase Jitter; 25MHz Integration Range: 100Hz - 1MHz		REF_SEL[1:0] = 10 or 11 <sup>3</sup>		0.191		ps
$t_{PD}$	Propagation Delay <sup>4</sup>	CLK0, nCLK0 or CLK1, nCLK1 to any Qx, nQx Outputs	SMODEA/B[1:0] = 00	0.225		0.80	ns
			SMODEA/B[1:0] = 01	0.275		0.80	ns
			SMODEA/B[1:0] = 10	0.9		2.80	ns
$t_{sk(o)}$	Output Skew <sup>5, 6</sup>					80	ps
$t_{sk(pp)}$	Part-to-Part Skew <sup>6, 7</sup>				200		ps
$V_{OH}$	Voltage High <sup>8, 9</sup>	HCSL Outputs	$T_A = 25^\circ C$ , DC Measurement, $R_T = 50\Omega$ to GND $C_L \leq 5pF$	520		920	mV
$V_{OL}$	Voltage Low <sup>8, 10</sup>	HCSL Outputs		-150		+150	mV
$V_{CROSS}$	Absolute Crossing Voltage <sup>8, 11, 12</sup>	HCSL Outputs	$R_T = 50\Omega$ to GND $C_L \leq 5pF$	160		460	mV
$\Delta V_{CROSS}$	Total Variation of $V_{CROSS}$ over all Edges <sup>8, 11, 13</sup>	HCSL Outputs				140	mV
	Rise/Fall Edge Rate <sup>3, 14, 15</sup>	HCSL Outputs		0.6		4.0	V/ns
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs	20% to 80%		150	300	ps
		LVDS Outputs	20% to 80%		150	300	ps
		HCSL Outputs	20% to 80%		400	650	ps
		REFOUT	20% to 80%		450	750	ps
odc	Output Duty Cycle <sup>16</sup>	with Crystal Input		45		55	%
		with external 50%/ 50% Duty Cycle Clock Input		45		55	%
MUX_ISOLATIO N	MUX Isolation		156.25MHz		75		dB

NOTE 1. Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 2. All LVDS and LVPECL parameters characterized up to 1.5GHz. HCSL parameters characterized up to 250MHz.

NOTE 3. Measurement taken from differential waveform.

NOTE 4. Measured from the differential input crosspoint to the differential output crosspoint.

NOTE 5. Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the differential cross-point.

NOTE 6. This parameter is defined in accordance with JEDEC Standard 65.

NOTE 7. Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross-point.

NOTE 8. Measurement taken from single-ended waveform.

NOTE 9. Defined as the maximum instantaneous voltage including overshoot.

NOTE 10. Defined as the minimum instantaneous voltage including undershoot.

NOTE 11. Measured at crosspoint where the instantaneous voltage value of the rising edge of Qx equals the falling edge of nQx.

NOTE 12. Refers to the total variation from the lowest crosspoint to the highest, regardless of which edge is crossing. Refers to all cross-point for this measurement.

NOTE 13. Defined as the total variation of all crossing voltages of rising Qx and falling nQx, This is the maximum allowed variance in Vcross for any particular system.

NOTE 14. Measured from -150mV to +150mV on the differential waveform (Qx minus nQx). The signal must be monotonic through the measurement region for rise and fall time. The 300mV measurement window is centered on the differential zero crossing.

NOTE 15. Measured at 100MHz.

NOTE 16. Measured for the following frequencies: 25MHz, 100MHz, 125MHz, 156.25MHz, 312.5MHz, 400MHz, and 644.5313MHz.



**Table 22: AC Characteristics,  $V_{DD} = V_{DDOA} = V_{DDOB} = V_{DDOREF} = 2.5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$  1, 2**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit	
$f_{OUT}$	Output Frequency	LVDS, LVPECL Outputs			2000	MHz	
		HCSL Outputs			250	MHz	
		REFOUT			250	MHz	
$t_{jit}$	Buffer Additive Phase Jitter, RMS: Integration Range 12kHz - 20MHz REF_SEL[1:0] = 00 or 01	Clock Frequency = 156.25MHz; Input Clock from 8T49NS010, Input Clock Jitter = 86.8fs; SMODEA/B[1:0] = 00		37.1		fs	
$t_{jit}(\emptyset)$	RMS Phase Jitter; 25MHz Integration Range: 100Hz - 1MHz	REF_SEL[1:0] = 10 or 11 <sup>3</sup>		0.371		ps	
NF	Noise Floor	LVPECL	Offset Freq. >10MHz; 156.25MHz Clock Freq.		-159		dBc/Hz
		LVDS			-157		dBc/Hz
		HCSL			-155		dBc/Hz
$t_{PD}$	Propagation Delay <sup>4</sup>	CLK0, nCLK0 or CLK1, nCLK1 to any Qx, nQx Outputs	SMODEA/B[1:0] = 00	0.275		0.75	ns
			SMODEA/B[1:0] = 01	0.275		0.75	ns
			SMODEA/B[1:0] = 10	0.9		2.80	ns
$t_{sk(o)}$	Output Skew <sup>5, 6</sup>				80	ps	
$t_{sk(pp)}$	Part-to-Part Skew <sup>6, 7</sup>			200		ps	
$V_{OH}$	Voltage High <sup>8, 9</sup>	HCSL Outputs	$T_A = 25^\circ C$ , DC Measurement, $R_T = 50\Omega$ to GND $C_L \leq 5pF$	520		920	mV
$V_{OL}$	Voltage Low <sup>8, 10</sup>	HCSL Outputs		-150		+150	mV
$V_{CROSS}$	Absolute Crossing Voltage <sup>8, 11, 12</sup>	HCSL Outputs	$R_T = 50\Omega$ to GND $C_L \leq 5pF$	160		460	mV
$\Delta V_{CROSS}$	Total Variation of $V_{CROSS}$ over all Edges <sup>8, 11, 13</sup>	HCSL Outputs				140	mV
	Rise/Fall Edge Rate <sup>3, 14, 15</sup>	HCSL Outputs		0.6		4.0	V/ns
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs	20% to 80%		150	300	ps
		LVDS Outputs	20% to 80%		150	300	ps
		HCSL Outputs	20% to 80%		400	650	ps
		REFOUT	20% to 80%		450	750	ps
odc	Output Duty Cycle <sup>16</sup>		With Crystal Input	45		55	%
			With external 50%/ 50% Duty Cycle Clock Input	45		55	%
MUX_ISOLATION	MUX Isolation	156.25MHz		75		dB	

NOTE 1. Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 2. All LVDS and LVPECL parameters characterized up to 1.5GHz. HCSL parameters characterized up to 250MHz.

NOTE 3. Measurement taken from differential waveform.

NOTE 4. Measured from the differential input crosspoint to the differential output crosspoint.

NOTE 5. Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the differential crosspoint.

NOTE 6. This parameter is defined in accordance with JEDEC Standard 65.

NOTE 7. Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross-point.

NOTE 8. Measurement taken from single-ended waveform.

NOTE 9. Defined as the maximum instantaneous voltage including overshoot.

NOTE 10. Defined as the minimum instantaneous voltage including undershoot.

NOTE 11. Measured at crosspoint where the instantaneous voltage value of the rising edge of Qx equals the falling edge of nQx.

NOTE 12. Refers to the total variation from the lowest crosspoint to the highest, regardless of which edge is crossing. Refers to all cross-point for this measurement.

NOTE 13. Defined as the total variation of all crossing voltages of rising Qx and falling nQx, This is the maximum allowed variance in Vcross for any particular system.

NOTE 14. Measured from -150mV to +150mV on the differential waveform (Qx minus nQx). The signal must be monotonic through the measurement region for rise and fall time. The 300mV measurement window is centered on the differential zero crossing.

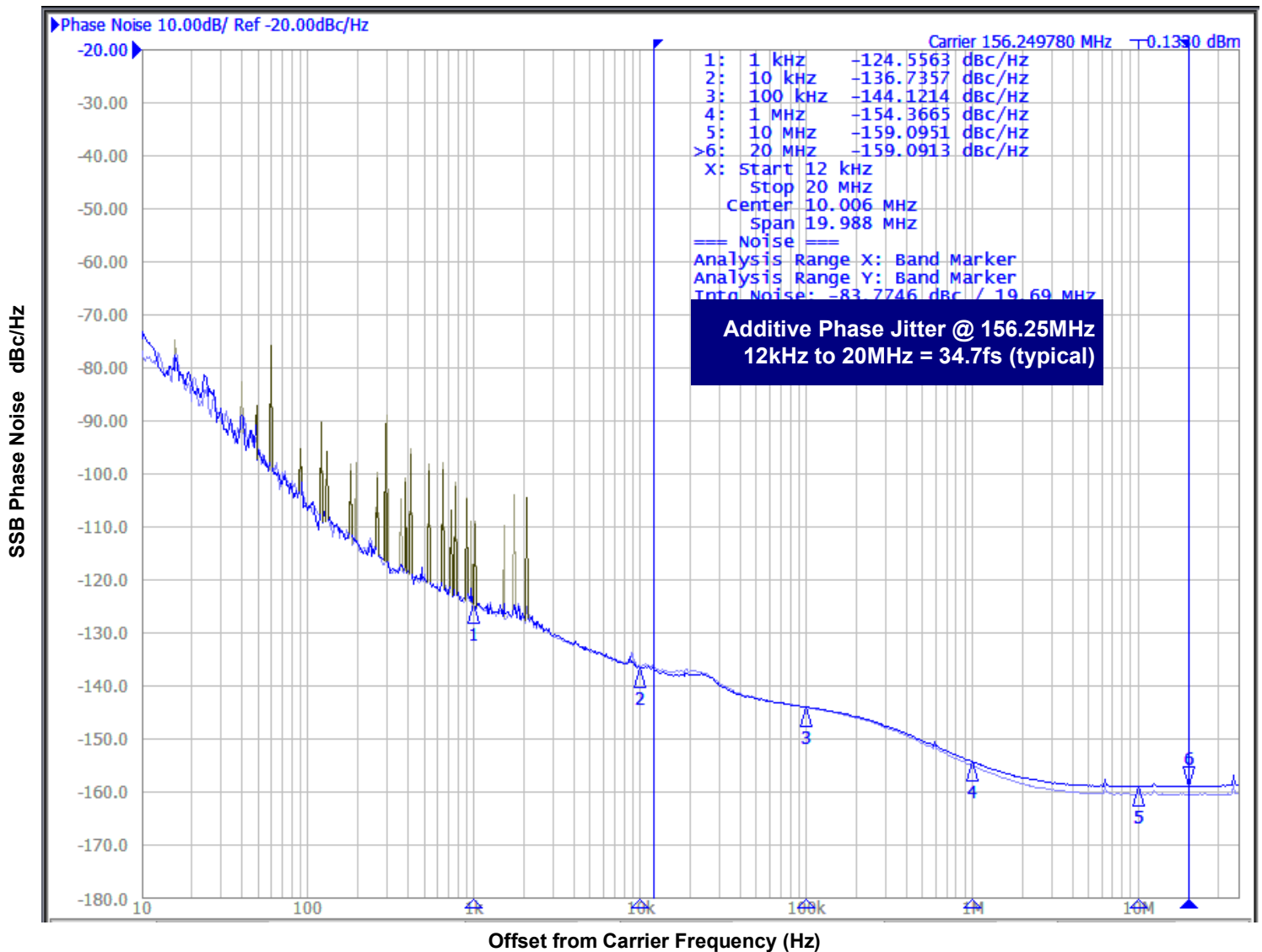
NOTE 15. Measured at 100MHz.

NOTE 16. Measured for the following frequencies: 25MHz, 100MHz, 125MHz, 156.25MHz, 312.5MHz, 400MHz, and 644.5313MHz.

## Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the **dBc Phase Noise**. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio

of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a **dBc** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



As with most timing specifications, phase noise measurements have issues relating to the limitations of the measurement equipment. The noise floor of the equipment can be higher or lower than the noise floor of the device. Additive phase noise is dependent on both the noise floor of the input source and measurement equipment.

The additive phase jitter for this device was measured using an IDT Clock Driver 8T49NS010 as an input source and Agilent E5052 phase noise analyzer.

## Applications Information

### Recommendations for Unused Input and Output Pins

#### Inputs:

##### CLK/nCLK<sup>-</sup>Inputs

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, 1kΩ resistors can be tied from CLK to ground and nCLK to V<sub>DD</sub>.

##### Crystal Inputs

For applications not requiring the use of the crystal oscillator input, both XTAL\_IN and XTAL\_OUT can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from XTAL\_IN to ground.

##### LVC MOS Control Pins

All control pins have internal pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

#### Outputs:

##### LVC MOS Output (REFOUT)

If LVC MOS output is not used, then disable the output and it can be left floating.

##### LVPECL and HC SL Outputs

Any unused output pairs can be left floating. We recommend that there is no trace attached.

##### LVDS Outputs

Any unused LVDS output pairs can be either left floating or terminated with 100Ω across. If they are left floating, we recommend that there is no trace attached.

##### Differential Outputs

If all the outputs of any bank are not used, then disable all outputs to High-Impedance.

### Crystal Input Interface

The 8T39S06A has been characterized with 18pF parallel resonant crystals. The capacitor values, C1 and C2, shown in *Figure 1* below were determined using an 18pF parallel resonant crystal and were chosen to minimize the ppm error. In addition, the recommended 12pF parallel resonant crystal tuning is shown in *Figure 2*. The optimum C1 and C2 values can be slightly adjusted for different board layouts.

### Power Up Ramp Sequence

This device has multiple supply pins dedicated for different blocks. Output power supplies V<sub>DDOx</sub> (V<sub>DDOA</sub>, V<sub>DDOB</sub>, V<sub>DDOREF</sub>) must ramp up before, or concurrently with core power supply V<sub>DD</sub>. All power supplies must ramp up in a linear fashion and monotonically. Both V<sub>DDOA</sub> and V<sub>DDOB</sub> power supplies must be powered-up even when only one bank of outputs is in use.

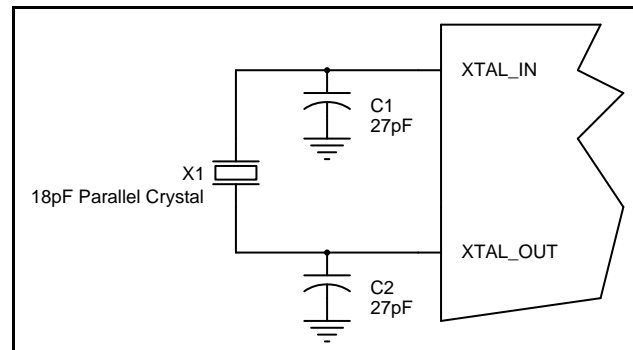


Figure 1. Crystal Input Interface

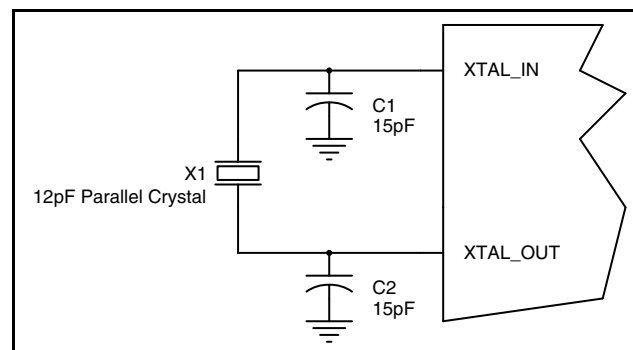


Figure 2. Crystal Input Interface

## Overdriving the XTAL Interface

The XTAL\_IN input can be overdriven by an LVCMOS driver or by one side of a differential driver through an AC coupling capacitor. The XTAL\_OUT pin can be left floating. The amplitude of the input signal should be between 500mV and 1.8V and the slew rate should not be less than 0.2V/ns. For 3.3V LVCMOS inputs, the amplitude must be reduced from full swing to at least half the swing in order to prevent signal interference with the power rail and to reduce internal noise. *Figure 3A* shows an example of the interface diagram for a high speed 3.3V LVCMOS driver. This configuration requires that the sum of the output impedance of the driver ( $R_o$ ) and the series resistance ( $R_s$ ) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This

can be done in one of two ways. First,  $R_1$  and  $R_2$  in parallel should equal the transmission line impedance. For most 50Ω applications,  $R_1$  and  $R_2$  can be 100Ω. This can also be accomplished by removing  $R_1$  and changing  $R_2$  to 50Ω. The values of the resistors can be increased to reduce the loading for a slower and weaker LVCMOS driver. *Figure 3B* shows an example of the interface diagram for an LVPECL driver. This is a standard LVPECL termination with one side of the driver feeding the XTAL\_IN input. It is recommended that all components in the schematics be placed in the layout. Though some components might not be used, they can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a quartz crystal as the input.

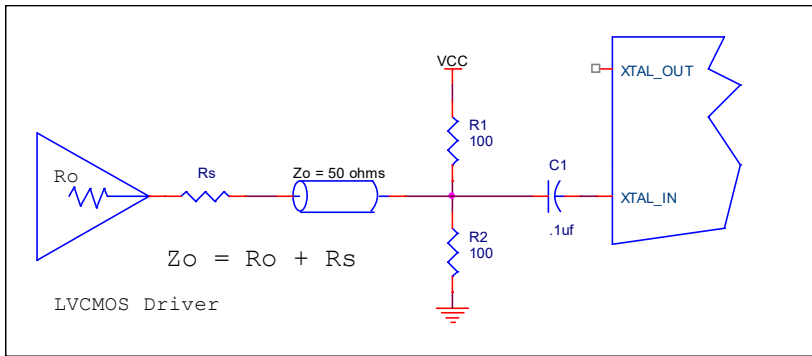


Figure 3A. General Diagram for LVCMOS Driver to XTAL Input Interface

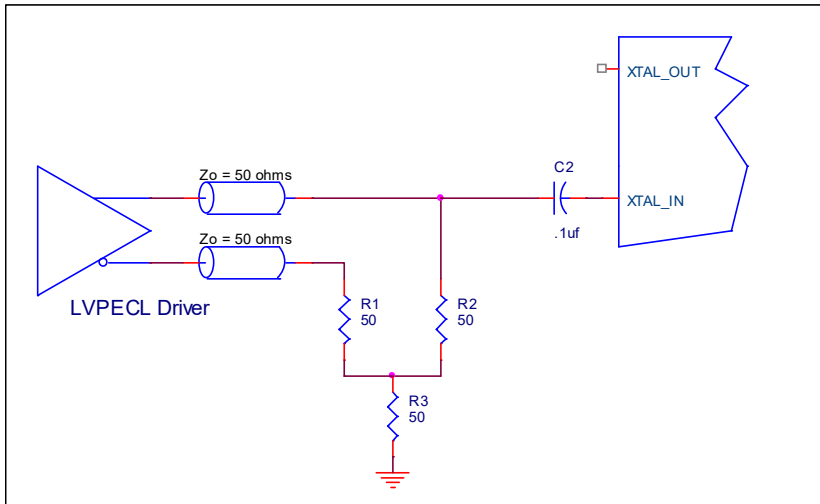


Figure 3B. General Diagram for LVPECL Driver to XTAL Input Interface

### Wiring the Differential Input to Accept Single-Ended Levels

Figure 4 shows how a differential input can be wired to accept single ended levels. The reference voltage  $V_1 = V_{DD}/2$  is generated by the bias resistors R1 and R2. The bypass capacitor (C1) is used to help filter noise on the DC bias. This bias circuit should be located as close to the input pin as possible. The ratio of R1 and R2 might need to be adjusted to position the  $V_1$  in the center of the input voltage swing. For example, if the input clock swing is 2.5V and  $V_{DD} = 3.3V$ , R1 and R2 value should be adjusted to set  $V_1$  at 1.25V. The values below are for when both the single ended swing and  $V_{DD}$  are at the same voltage. This configuration requires that the sum of the output impedance of the driver ( $R_o$ ) and the series resistance ( $R_s$ ) equals the transmission line impedance. In addition, matched termination at the input will attenuate the signal in half. This can be done in one of two ways. First, R3 and R4 in parallel should equal the transmission

line impedance. For most 50Ω applications, R3 and R4 can be 100Ω. The values of the resistors can be increased to reduce the loading for slower and weaker LVCMOS driver. When using single-ended signaling, the noise rejection benefits of differential signaling are reduced. Even though the differential input can handle full rail LVCMOS signaling, it is recommended that the amplitude be reduced. The datasheet specifies a lower differential amplitude, however this only applies to differential signals. For single-ended applications, the swing can be larger, however  $V_{IL}$  cannot be less than -0.3V and  $V_{IH}$  cannot be more than  $V_{DD} + 0.3V$ . Though some of the recommended components might not be used, the pads should be placed in the layout. They can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a differential signal.

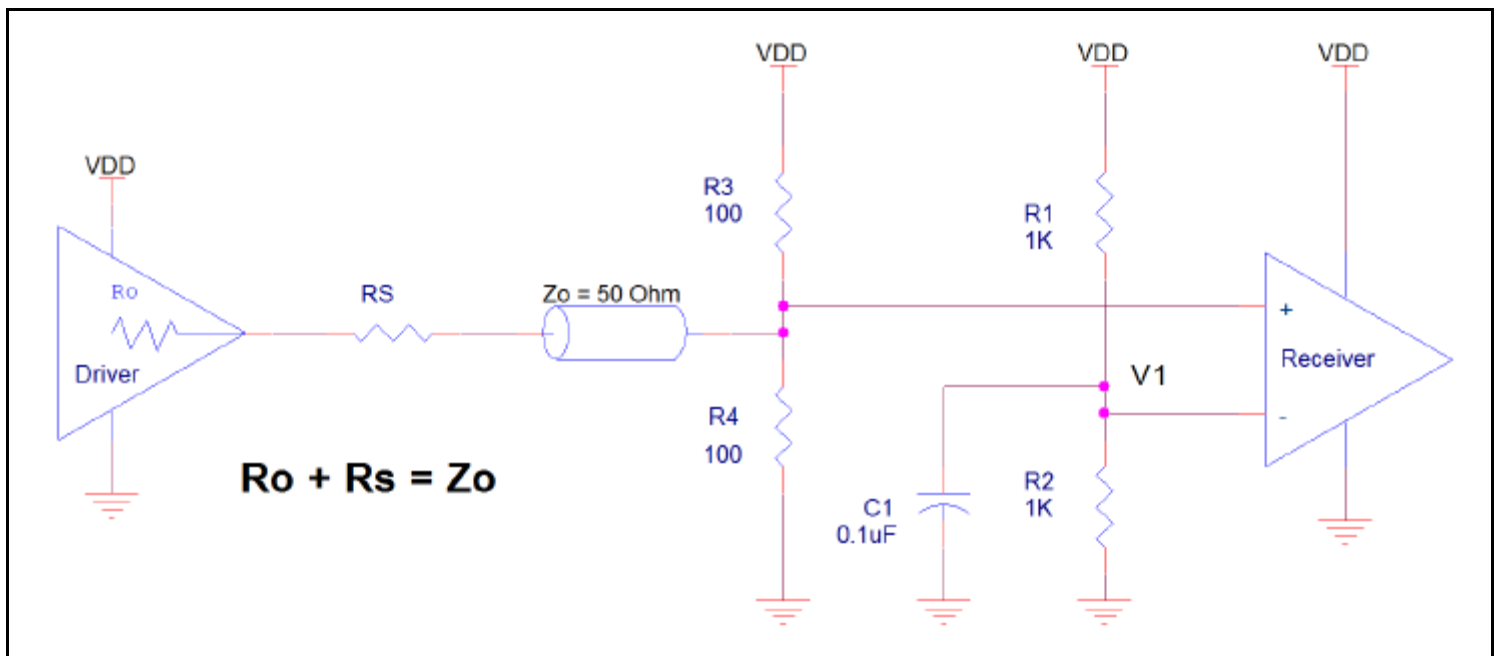
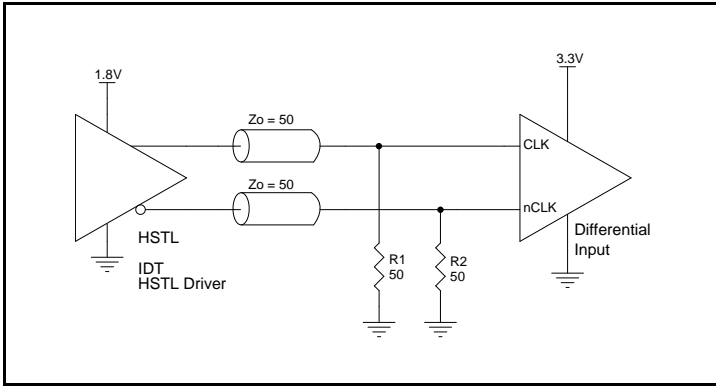


Figure 4. Recommended Schematic for Wiring a Differential Input to Accept Single-ended Levels

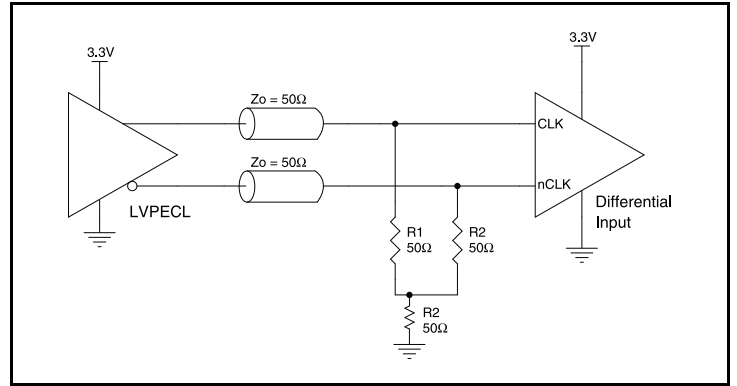
### 3.3V Differential Clock Input Interface

The CLK/nCLK accepts LVDS, LVPECL, HSTL and other differential signals. Both differential inputs must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. *Figures 5A to 5E* show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the

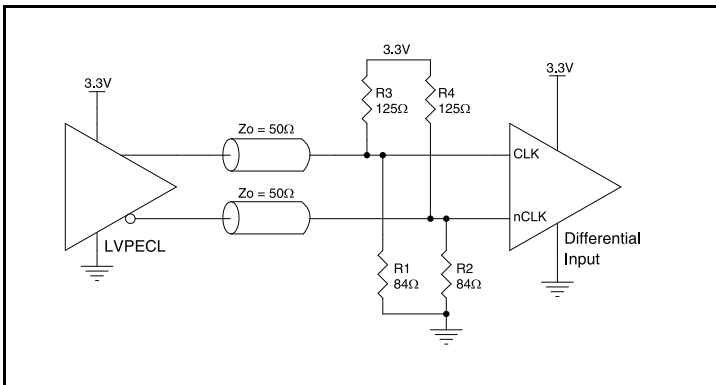
vendor of the driver component to confirm the driver termination requirements. For example, in Figure 5A, the input termination applies for IDT open emitter HSTL drivers. If you are using an HSTL driver from another vendor, use their termination recommendation.



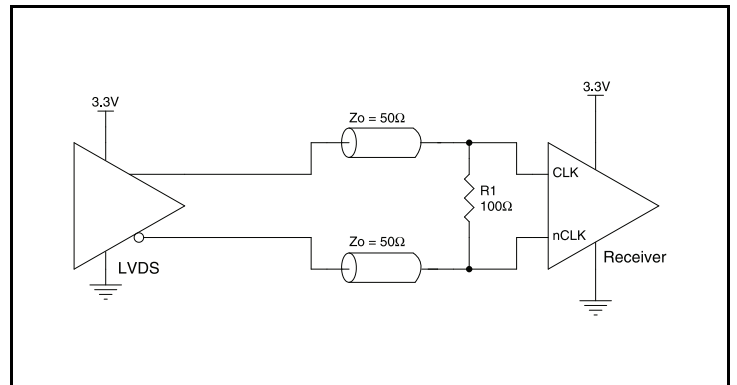
**Figure 5A.** CLK/nCLK Input Driven by an IDT Open Emitter HSTL Driver



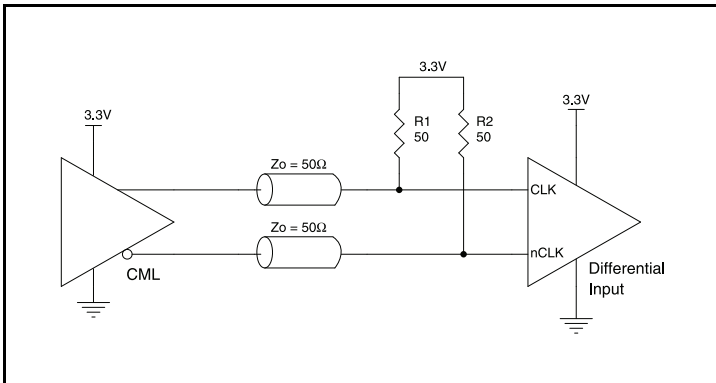
**Figure 5B.** CLK/nCLK Input Driven by a 3.3V LVPECL Driver



**Figure 5C.** CLK/nCLK Input Driven by a 3.3V LVPECL Driver



**Figure 5D.** CLK/nCLK Input Driven by a 3.3V LVDS Driver

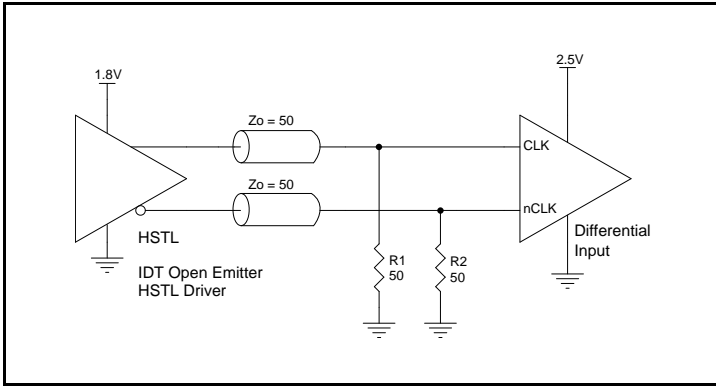


**Figure 5E.** CLK/nCLK Input Driven by an IDT Open Collector CML Driver

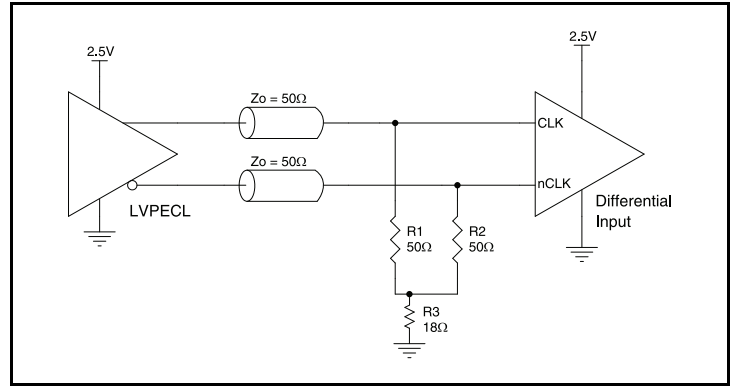
## 2.5V Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, HSTL, HCSSL and other differential signals. Both  $V_{SWING}$  and  $V_{OH}$  must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. *Figures 6A to 6E* show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult

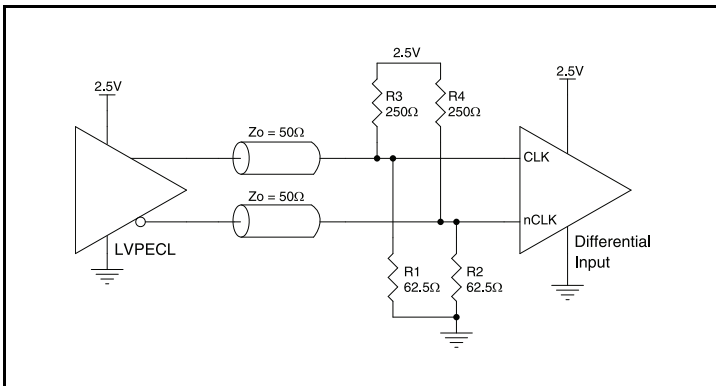
with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 6A, the input termination applies for IDT open emitter HSTL drivers. If you are using an HSTL driver from another vendor, use their termination recommendation.



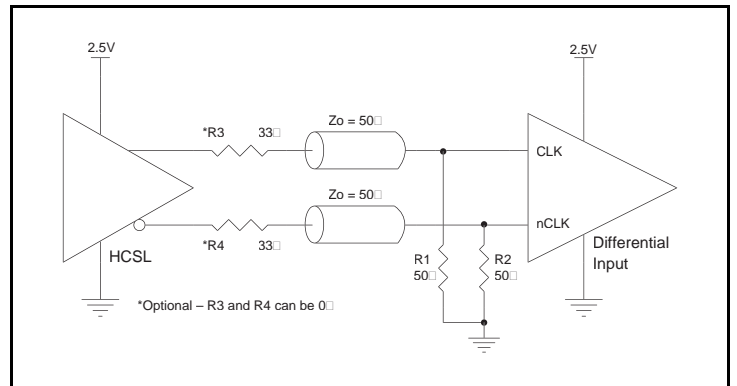
**Figure 6A.** CLK/nCLK Input Driven by an IDT Open Emitter HSTL Driver



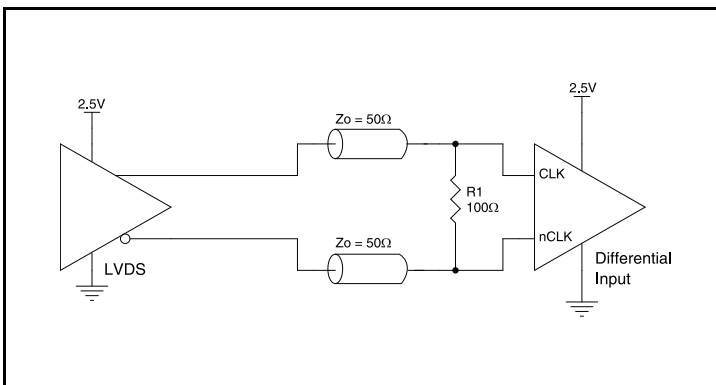
**Figure 6B.** CLK/nCLK Input Driven by a 2.5V LVPECL Driver



**Figure 6C.** CLK/nCLK Input Driven by a 2.5V LVPECL Driver



**Figure 6D.** CLK/nCLK Input Driven by a 2.5V HCSSL Driver



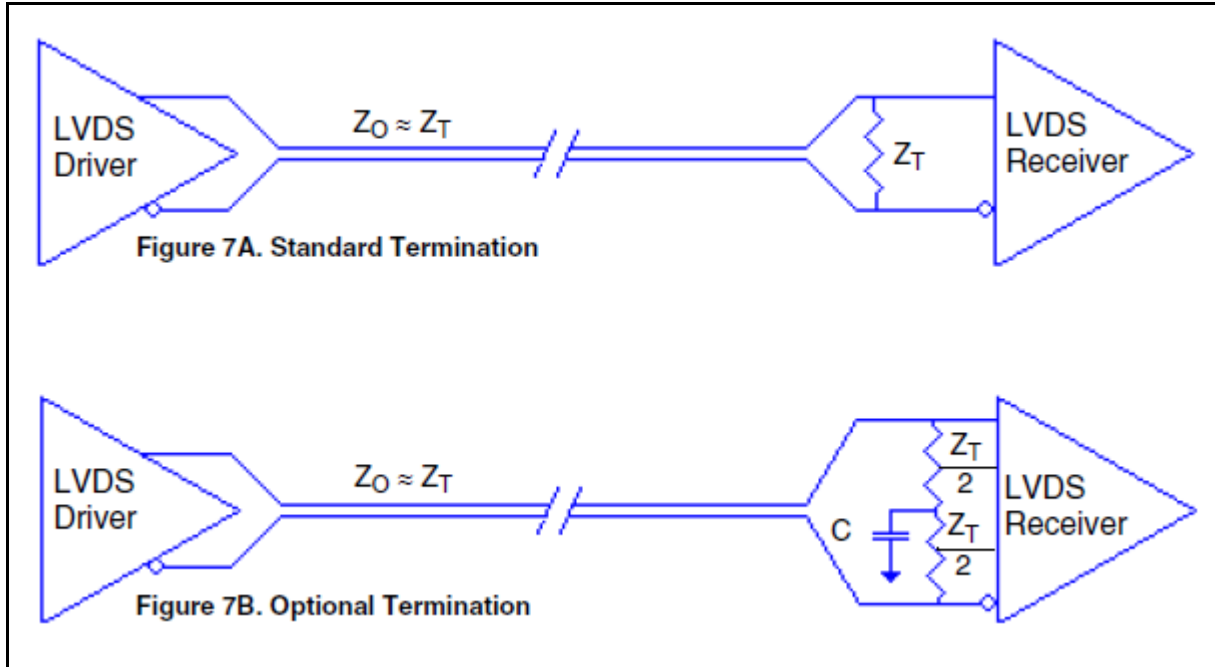
**Figure 6E.** CLK/nCLK Input Driven by a 2.5V LVDS Driver



## LVDS Driver Termination

For a general LVDS interface, the recommended value for the termination impedance ( $Z_T$ ) is between  $90\Omega$  and  $132\Omega$ . The actual value should be selected to match the differential impedance ( $Z_0$ ) of your transmission line. A typical point-to-point LVDS design uses a  $100\Omega$  parallel resistor at the receiver and a  $100\Omega$  differential transmission-line environment. In order to avoid any transmission-line reflection issues, the components should be surface mounted and must be placed as close to the receiver as possible. IDT offers a full line of LVDS compliant devices with two types of output structures: current source and voltage source. The

standard termination schematic as shown in *Figure 7A* can be used with either type of output structure. *Figure 7B*, which can also be used with both output types, is an optional termination with center tap capacitance to help filter common mode noise. The capacitor value should be approximately  $50\text{pF}$ . If using a non-standard termination, it is recommended to contact IDT and confirm if the output structure is current source or voltage source type. In addition, since these outputs are LVDS compatible, the input receiver's amplitude and common-mode input range should be verified for compatibility with the output.



LVDS Termination

### Termination for 3.3V LVPECL Outputs

The clock topology shown below is a typical termination for LVPECL outputs. The two different terminations mentioned are recommended only as guidelines.

The differential outputs are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating

resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion.

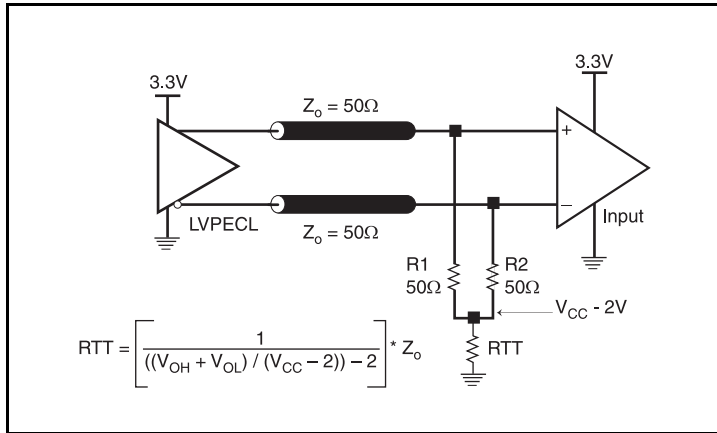


Figure 8A. 3.3V LVPECL Output Termination

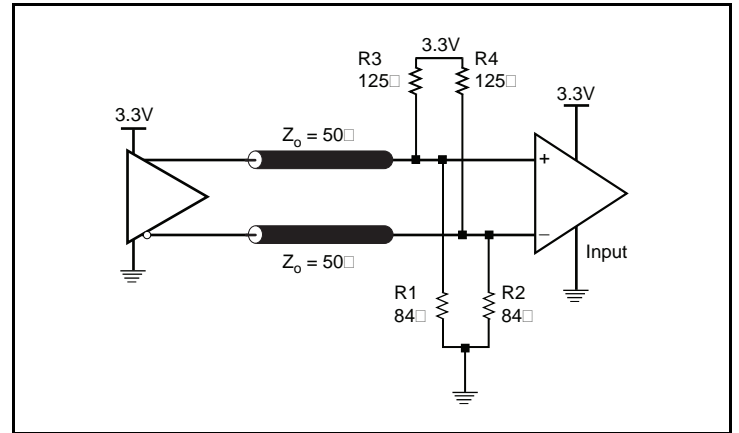


Figure 8B. 3.3V LVPECL Output Termination

### Termination for 2.5V LVPECL Outputs

Figure 9A and Figure 9B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating  $50\Omega$  to  $V_{DDO} - 2V$ . For  $V_{DDO} = 2.5V$ , the  $V_{DDO} - 2V$  is very close to ground

level. The R3 in Figure 9B can be eliminated and the termination is shown in Figure 9C.

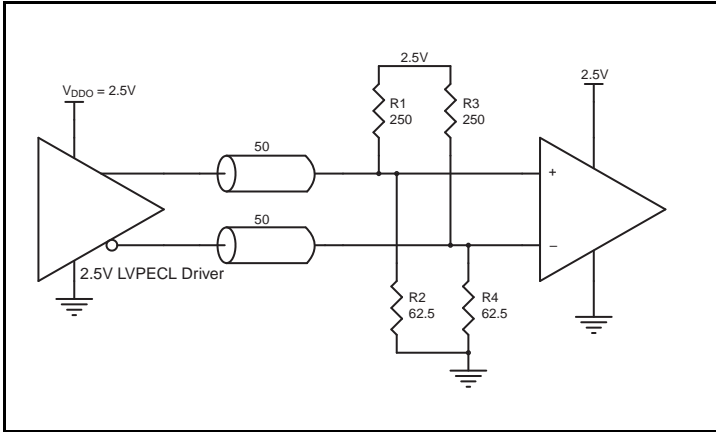


Figure 9A. 2.5V LVPECL Driver Termination Example

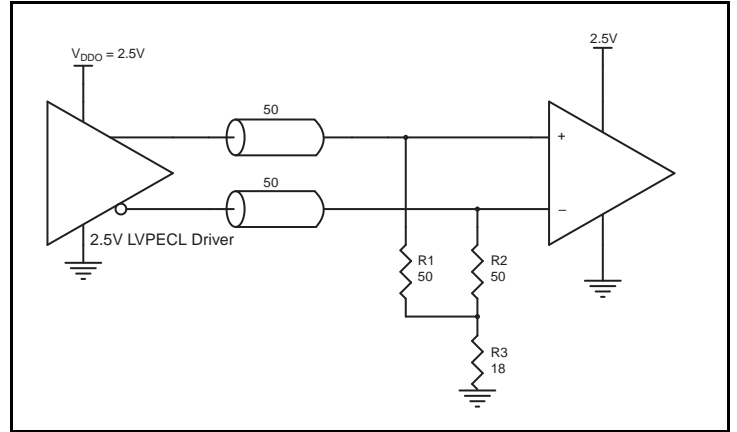


Figure 9B. 2.5V LVPECL Driver Termination Example

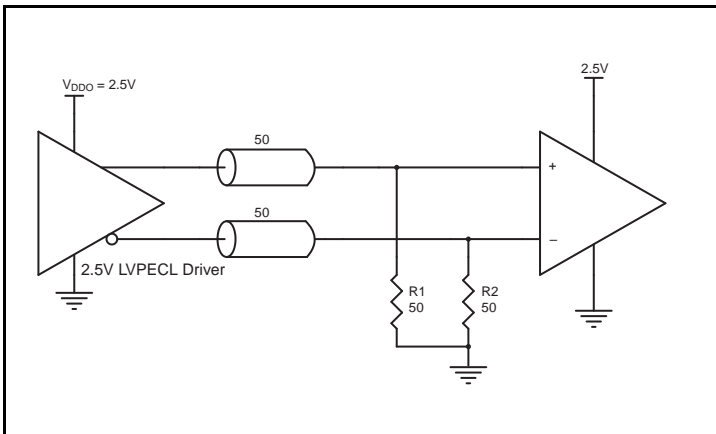
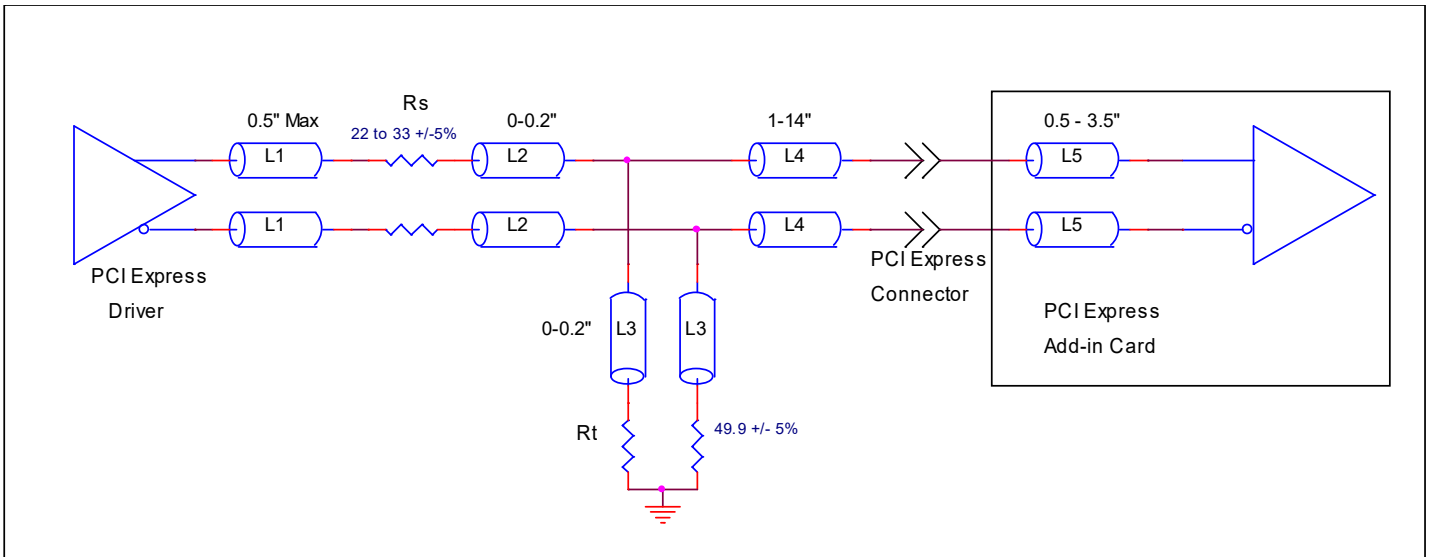


Figure 9C. 2.5V LVPECL Driver Termination Example

### Recommended Termination

Figure 10A is the recommended source termination for applications where the driver and receiver will be on a separate PCBs. This termination is the standard for PCI Express™ and HCSL output

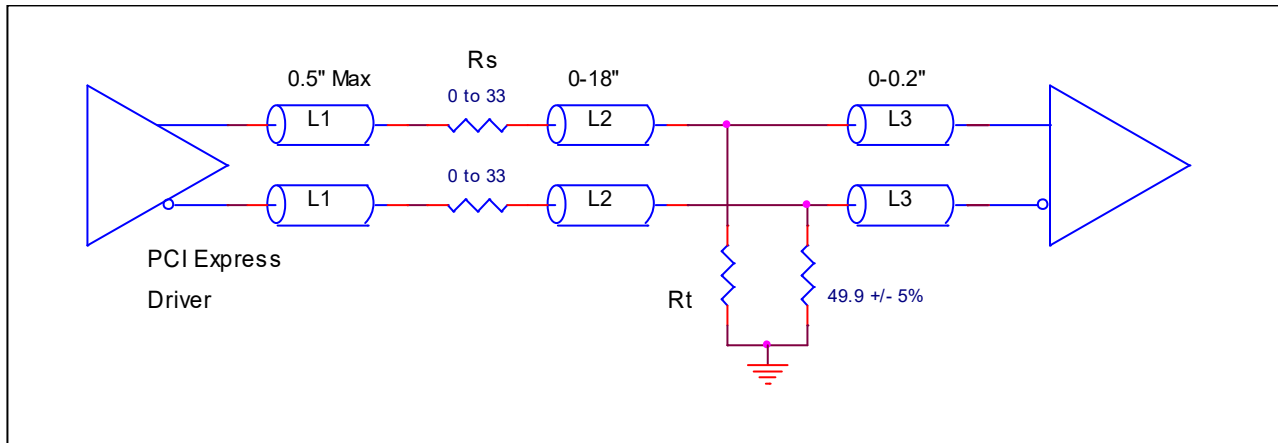
types. All traces should be 50Ω impedance single-ended or 100Ω differential.



**Figure 10A. Recommended Source Termination (where the driver and receiver will be on separate PCBs)**

Figure 10B is the recommended termination for applications where a point-to-point connection can be used. A point-to-point connection contains both the driver and the receiver on the same PCB. With a matched termination at the receiver, transmission-line reflections will

be minimized. In addition, a series resistor (Rs) at the driver offers flexibility and can help dampen unwanted reflections. The optional resistor can range from 0Ω to 33Ω. All traces should be 50Ω impedance single-ended or 100Ω differential.



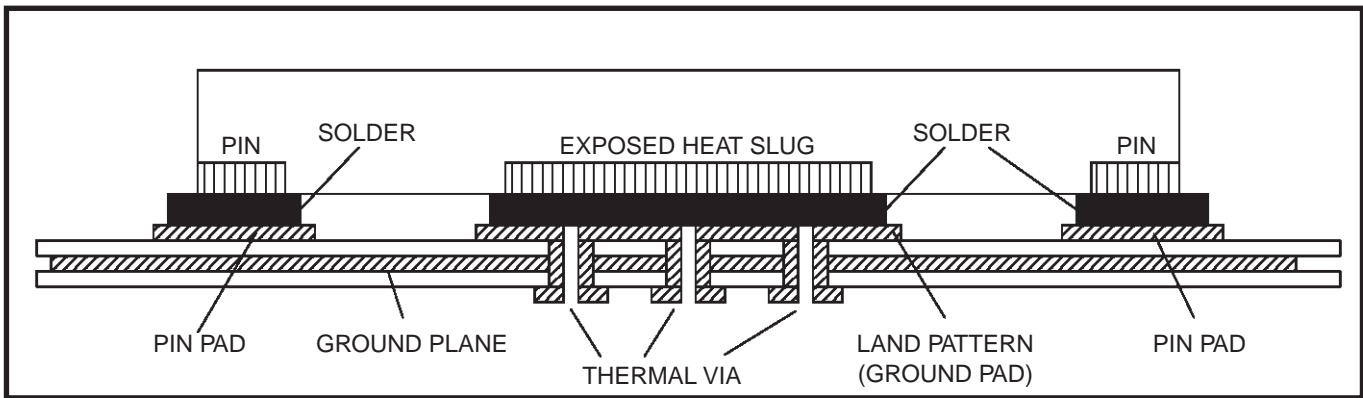
**Figure 10B. Recommended Termination (where a point-to-point connection can be used)**

### VFQFN EPAD Thermal Release Path

In order to maximize both the removal of heat from the package and the electrical performance, a land pattern must be incorporated on the Printed Circuit Board (PCB) within the footprint of the package corresponding to the exposed metal pad or exposed heat slug on the package, as shown in *Figure 11*. The solderable area on the PCB, as defined by the solder mask, should be at least the same size/shape as the exposed pad/slug area on the package to maximize the thermal/electrical performance. Sufficient clearance should be designed on the PCB between the outer edges of the land pattern and the inner edges of pad pattern for the leads to avoid any shorts.

While the land pattern on the PCB provides a means of heat transfer and electrical grounding from the package to the board through a solder joint, thermal vias are necessary to effectively conduct from the surface of the PCB to the ground plane(s). The land pattern must be connected to ground through these vias. The vias act as “heat pipes”. The number of vias (i.e. “heat pipes”) are application specific

and dependent upon the package power dissipation as well as electrical conductivity requirements. Thus, thermal and electrical analysis and/or testing are recommended to determine the minimum number needed. Maximum thermal and electrical performance is achieved when an array of vias is incorporated in the land pattern. It is recommended to use as many vias connected to ground as possible. It is also recommended that the via diameter should be 12 to 13mils (0.30 to 0.33mm) with 1oz copper via barrel plating. This is desirable to avoid any solder wicking inside the via during the soldering process which may result in voids in solder between the exposed pad/slug and the thermal land. Precautions should be taken to eliminate any solder voids between the exposed heat slug and the land pattern. Note: These recommendations are to be used as a guideline only. For further information, please refer to the Application Note on the Surface Mount Assembly of Amkor’s Thermally/Electrically Enhance Lead frame Base Package, Amkor Technology.



**Figure 11. P.C. Assembly for Exposed Pad Thermal Release Path – Side View (drawing not to scale)**

## Power Considerations

This section provides information on power dissipation and junction temperature for the 8T39S06A. Equations and example calculations are also provided.

### LVPECL Power Considerations

#### 1. Power Dissipation.

The total power dissipation for the 8T39S06A is the sum of the core power plus the power dissipated due to outputs switching. The following is the power dissipation for  $V_{DD} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

The Maximum current at 85°C is as follows:

$$I_{EE\_MAX} = 155mA$$

- Power (core)<sub>MAX</sub> =  $I_{EE\_MAX} * V_{DD\_MAX} = 3.465V * 155mA = \mathbf{537.035mW}$
- Power (outputs)<sub>MAX</sub> = **30mW/Loaded Output pair**

If all outputs are loaded, the total power is  $6 * 32mW = \mathbf{192mW}$ .

Maximum Core and LVPECL power dissipation =  $537.035mW + 192mW = \mathbf{729.075mW}$

### LVC MOS Output Power Dissipation

- Static Power Dissipation: Power<sub>(static)MAX</sub> =  $V_{DDOREF\_MAX} * I_{DDREF\_MAX} = 3.465V * 2mA = \mathbf{6.93mW}$   
( $I_{DDREF\_MAX} = 2mA$ )
- Dynamic Power Dissipation at 250MHz
- Power (Dynamic)<sub>MAX</sub> =  $C_{PD} * Frequency * N * V_{DDOREF}^2 = 5.3pF * 250MHz * 1 * 3.465^2 = \mathbf{15.9mW}$   
LVC MOS Power Dissipation =  $6.93mW + 15.9mW = 22.84mW$
- LVC MOS Power Dissipation =  $6.93mW + 15.9mW = \mathbf{22.84mW}$

Total Power Dissipation =  $729.075mW + 22.84mW = 751.92mW$

#### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature,  $T_j$ , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 35°C/W per Table 23 below. Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.752W * 35^\circ C/W = 111.3^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

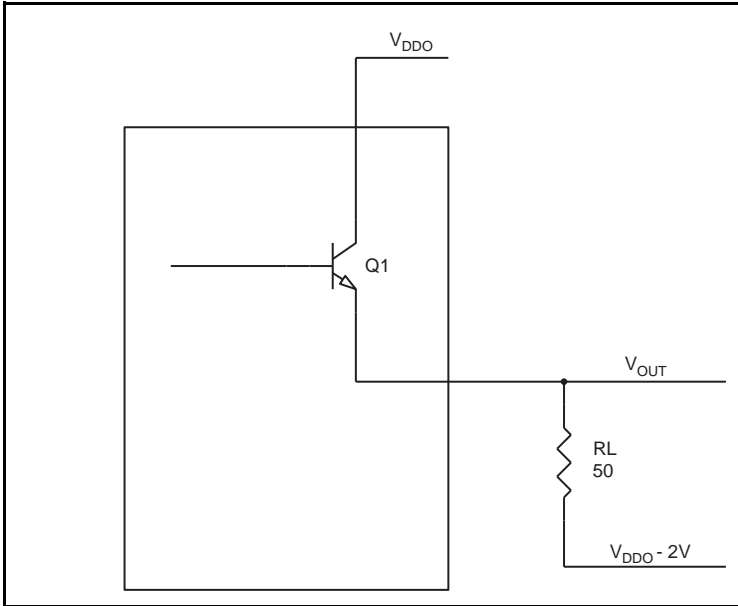
**Table 23: Thermal Resistance  $\theta_{JA}$  for 36-Lead VFQFN**

$\theta_{JA}$ vs. Air Flow			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	35°C/W	28.7°C/W	26.4°C/W

**3. Calculations and Equations.**

The purpose of this section is to calculate the power dissipation for the LVPECL output pairs.

LVPECL output driver circuit and termination are shown in *Figure 12*.



**Figure 12. LVPECL Driver Circuit and Termination**

To calculate power dissipation per output pair due to loading, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{DDO} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{DDO\_MAX} - 0.8V$   
 $(V_{DDO\_MAX} - V_{OH\_MAX}) = 0.8V$
- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{DDO\_MAX} - 1.6V$   
 $(V_{DDO\_MAX} - V_{OL\_MAX}) = 1.6V$

$Pd\_H$  is power dissipation when the output drives high.

$Pd\_L$  is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{DDO\_MAX} - 2V))/R_L] * (V_{DDO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{DDO\_MAX} - V_{OH\_MAX}))/R_L] * (V_{DDO\_MAX} - V_{OH\_MAX}) = [(2V - 0.8V)/50\Omega] * 0.8V = \mathbf{19.20mW}$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{DDO\_MAX} - 2V))/R_L] * (V_{DDO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{DDO\_MAX} - V_{OL\_MAX}))/R_L] * (V_{DDO\_MAX} - V_{OL\_MAX}) = [(2V - 1.6V)/50\Omega] * 1.6V = \mathbf{12.80mW}$$

$$\text{Total Power Dissipation per output pair} = Pd\_H + Pd\_L = 32mW$$

## Power Considerations

This section provides information on power dissipation and junction temperature for the 8T39S06A. Equations and example calculations are also provided.

### LVDS Power Considerations

#### 1. Power Dissipation.

The total power dissipation for the 8T39S06A is the sum of the core power plus the power dissipated due to outputs switching. The following is the power dissipation for  $V_{DD} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

The Maximum current at 85°C is as follows:

$$I_{DD\_MAX} = 105mA$$

$$I_{DDO\_MAX} = 140mA$$

- Power (core and output)<sub>MAX</sub> =  $V_{DD\_MAX} * (I_{DD\_MAX} + I_{DDO\_MAX}) = 3.465V * (105mA + 140mA) = \mathbf{848.925mW}$ .

### LVC MOS Output Power Dissipation

- Static Power Dissipation: Power<sub>(static)MAX</sub> =  $V_{DDOREF\_MAX} * I_{DDREF\_MAX} = 3.465V * 2mA = \mathbf{6.93mW}$   
( $I_{DDREF\_MAX} = 2mA$ )
- Dynamic Power Dissipation at 250MHz
- Power (Dynamic)<sub>MAX</sub> =  $C_{PD} * \text{Frequency} * N * V_{DDOREF}^2 = 5.3pF * 250MHz * 1 * 3.465^2 = \mathbf{15.9mW}$
- LVC MOS Power Dissipation =  $6.93mW + 15.9mW = \mathbf{22.84mW}$

$$\text{Total Power Dissipation} = 848.925mW + 22.84mW = 871.765mW$$

#### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature,  $T_j$ , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 35°C/W per Table 8. Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.872W * 35^\circ C/W = 115.5^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

**Table 8. Thermal Resistance  $\theta_{JA}$  for 36-Lead VFQFN**

$\theta_{JA}$ vs. Air Flow			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	35°C/W	28.7°C/W	26.4°C/W



## Power Considerations

This section provides information on power dissipation and junction temperature for the 8T39S06A. Equations and example calculations are also provided.

### HCSL Power Considerations

#### 1. Power Dissipation.

The total power dissipation for the 8T39S06A is the sum of the core power plus the power dissipated due to outputs switching. The following is the power dissipation for  $V_{DD} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

The Maximum current at 85°C is as follows:

$$I_{DD\_MAX} = 100mA$$

$$I_{DDO\_MAX} = 60mA \text{ (Applications Frequency = 250MHz)}$$

- Power (core)<sub>MAX</sub> =  $V_{DD\_MAX} * (I_{DD\_MAX} + I_{DDO\_MAX}) = 3.465V * (100mA + 60mA) = \mathbf{554.4mW}$
- Power (outputs)<sub>MAX</sub> = **44.5mW/Loaded Output pair**

If all outputs are loaded, the total power is  $6 * 44.5mW = \mathbf{267mW}$ .

Maximum Core and HCSL power dissipation =  $554.4mW + 267mW = 821.4mW$

### LVC MOS Output Power Dissipation

- Static Power Dissipation: Power<sub>(static)MAX</sub> =  $V_{DDOREF\_MAX} * I_{DDREF\_MAX} = 3.465V * 2mA = \mathbf{6.93mW}$   
( $I_{DDREF\_MAX} = 2mA$ )
- Dynamic Power Dissipation at 250MHz
- Power (Dynamic)<sub>MAX</sub> =  $C_{PD} * \text{Frequency} * N * V_{DDOREF}^2 = 5.3pF * 250MHz * 1 * 3.465^2 = \mathbf{15.9mW}$
- LVC MOS Power Dissipation =  $6.93mW + 15.9mW = \mathbf{22.84mW}$

Total Power Dissipation =  $821.4mW + 22.84mW = \mathbf{844.24mW}$

#### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature,  $T_j$ , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 35°C/W per Table 9. Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.844W * 35^\circ C/W = 114.5^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

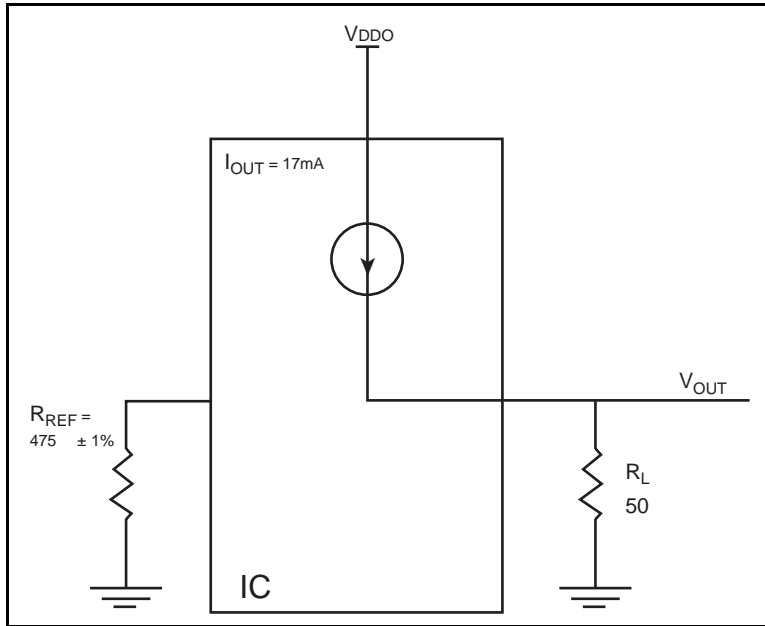
**Table 24: Thermal Resistance  $\theta_{JA}$  for 36-Lead VFQFN**

$\theta_{JA}$ vs. Air Flow			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	35°C/W	28.7°C/W	26.4°C/W

**3. Calculations and Equations.**

The purpose of this section is to calculate power dissipation on the IC per HCSL output pair.

HCSL output driver circuit and termination are shown in *Figure 13*.



**Figure 13. HCSL Driver Circuit and Termination**

HCSL is a current steering output which sources a maximum of 17mA of current per output. To calculate worst case on-chip power dissipation, use the following equations which assume a 50Ω load to ground.

The highest power dissipation occurs when  $V_{DDO\_MAX}$ .

$$\begin{aligned}
 \text{Power} &= (V_{DDO\_MAX} - V_{OUT}) * I_{OUT}, \\
 \text{since } V_{OUT} &= I_{OUT} * R_L \\
 &= (V_{DDO\_MAX} - I_{OUT} * R_L) * I_{OUT} \\
 &= (3.465V - 17mA * 50\Omega) * 17mA
 \end{aligned}$$

Total Power Dissipation per output pair = **44.5mW**

## Reliability Information

Table 25:  $\theta_{JA}$  vs. Air Flow Table for a 36 Lead VFQFN

$\theta_{JA}$ vs. Air Flow			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	35°C/W	28.7°C/W	26.4°C/W

## Transistor Count

The transistor count for 8T39S06A is: 10,283

## Package Outline Drawings

The package outline drawings are located at the end of this document and are accessible from the Renesas website (see [Ordering Information](#) for POD links). The package information is the most current data available and is subject to change without revision of this document.

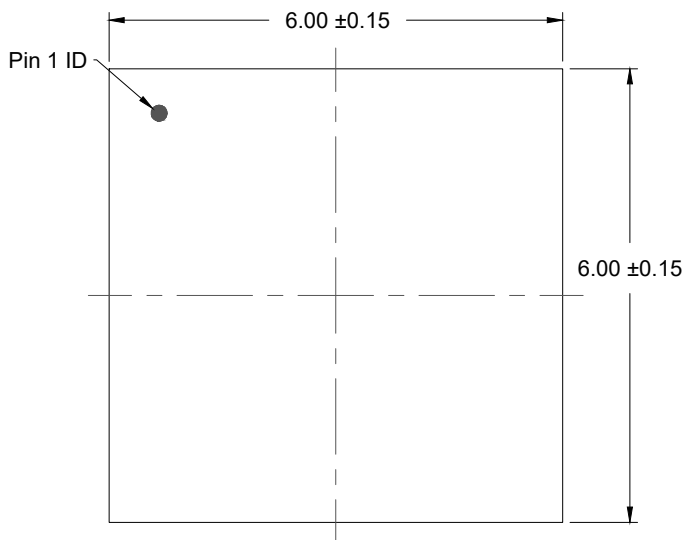
## Ordering Information

Table 11. Ordering Information

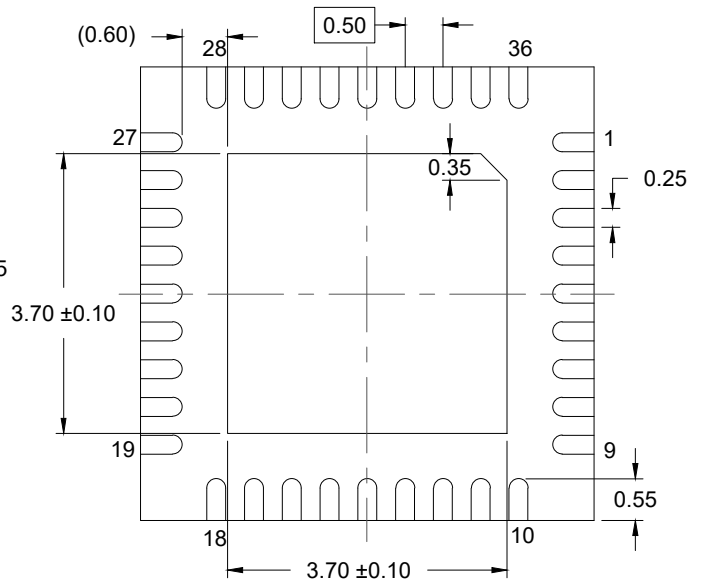
Part Number	Marking	Package Description	Carrier Type	Temperature Range
8T39S06ANBGI	IDT8T39S06ANBGI	<a href="#">36-VFQFPN</a> , Lead-Free	Tray	-40°C to +85°C
8T39S06ANBGI8	IDT8T39S06ANBGI	<a href="#">36-VFQFPN</a> , Lead-Free	Tape & Reel	-40°C to +85°C

## Revision History

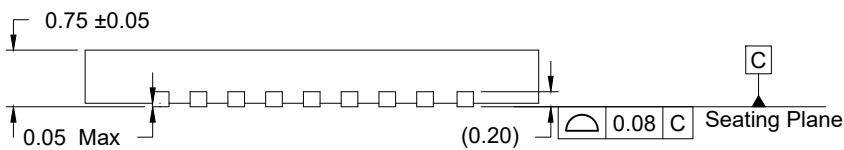
Date	Description
November 27, 2023	Updated Output State for Input Status – 01, CLK1 is high, nCLK1 is low to QB[2:0] = High, nQB[2:0] = low in <a href="#">Table 7</a> .
April 17, 2023	<ul style="list-style-type: none"> <li>Updated VCMR minimum to “GND” from “GND+0.5” in <a href="#">Table 14</a>.</li> <li>Added footnote “<math>V_{IL} &gt; -0.3V</math>” to <a href="#">Table 14</a>.</li> <li>Updated <a href="#">Package Outline Drawings</a> section.</li> </ul>
May 20, 2016	Initial release.



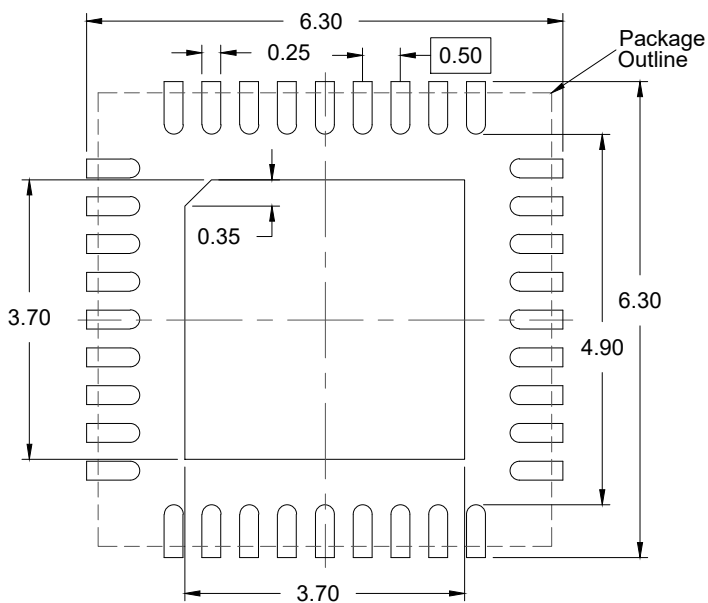
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN  
(PCB Top View, NSMD Design)

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use  $\pm 0.05$  mm for the non-toleranced dimensions.
4. Numbers in ( ) are for references only.

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